

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4949064

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
GABRIEL LI	08/22/2006
RECEIVING PARTY DATA	
Name:	Cypress Semiconductor Corporation
Street Address:	198 Champion Court
City:	San Jose
State/Country:	CALIFORNIA
Postal Code:	95134
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12577477
CORRESPONDENCE DATA	
Fax Number:	(408)545-6911
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	408-943-6878
Email:	cmrl@cypress.com, patents@cypress.com
Correspondent Name:	CYPRESS SEMICONDUCTOR CORPORATION
Address Line 1:	198 CHAMPION COURT
Address Line 4:	SAN JOSE, CALIFORNIA 95134
ATTORNEY DOCKET NUMBER:	CD05110C1
NAME OF SUBMITTER:	KIN HUNG LAI
SIGNATURE:	/Kin Hung Lai/
DATE SIGNED:	05/07/2018
Total Attachments: 2	
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ASSIGNMENT

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned, does hereby:

SELL, ASSIGN AND TRANSFER to CYPRESS SEMICONDUCTOR CORP. (the "Assignee"), having a place of business at 198 Champion Court, San Jose, CA. 95134 the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith, and is entitled "CIRCUIT, SYSTEM, AND METHOD FOR MULTIPLEXING SIGNALS WITH REDUCED JITTER." such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee; and

COVENANT AND AGREE that the above is and will be binding on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

FURTHER COVENANT that all statements made of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under the United States Code, Title 18 § 1001, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

(Signature) Gabriel Li
Gabriel Li

Date: 8-22-06

Please direct all communication as follows:

Customer No. 35617
Daffer McDaniel LLP
P.O. Box 684908
Austin, Texas 78768-4908
Ph: (512) 476-1400